Solutions for Your Better Assembly.

AlphaPro™

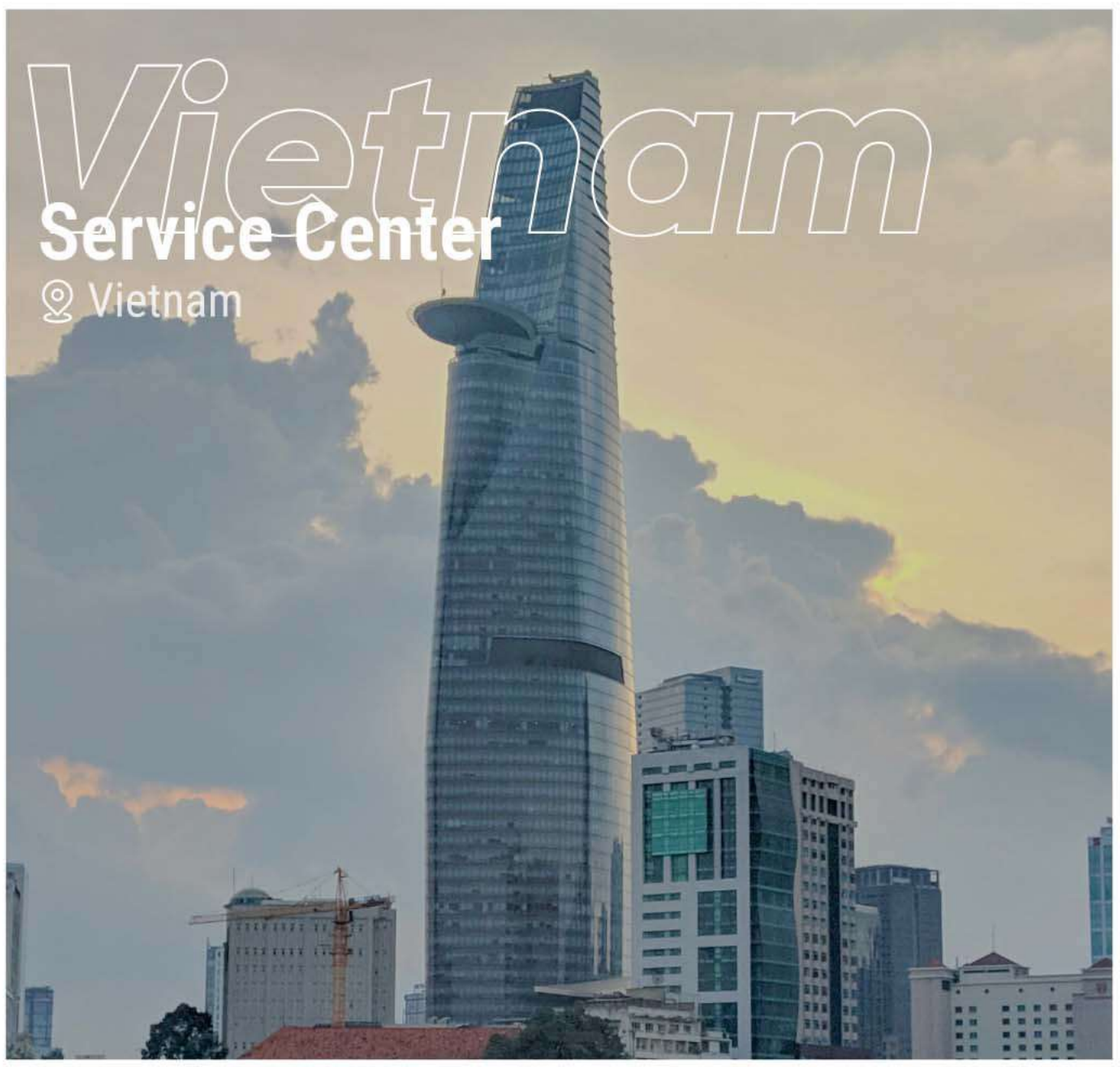
Industrial Adhesives and Tapes


Hong Kong
Global Headquarters
Hong Kong


Shenzhen
Operation Center
Shenzhen


Dongguan
Manufacturing Center
Dongguan


Shanghai
Reliable Analysis Laboratory
Shanghai


Vietnam
Service Center
Vietnam


Germany
Technical Support Center
Germany

150+

Over 150 innovative adhesive products can be offered

60%+

Over 60% of members are from assembly engineering with know-how

15+

Over 15 years know-how by core team engaged in adhesive industry

25%+

More than 25% cost can be reduced by adopting AlphaPro's solutions

AlphaPro Technology is a leading firm in assembly functional materials. Our business includes structural bonding, module packaging, thermal management, and conductive shielding. We collaborate with renowned universities like the University of Hong Kong, Northwestern University, Technische Universität München. This cooperation helps us achieve faster innovation.

We have mature packaging solutions in various cutting-edge industries such as semiconductors, consumer electronics, new energy, optoelectronic display, communications, and medical devices. At the same time, we have operation centers, sales centers, production bases, and R & D laboratories in Hong Kong, Shenzhen, Dongguan, and Shanghai; with service support centers in Vietnam and Germany, enabling us to provide flexible and immediate support to customers around the world.

Our corporate mission is to provide the most cost-effective products and highest quality services for the advanced manufacturing industry, and our values are - PES "Professional, Efficient, Synergetic".

Electronic-grade Adhesive

Polyurethane

PUR as a typical product of AlphaPro adhesive series is known for its exceptional bonding strength and versatility across various substrates. It is characterized by its resistance to chemicals and environmental aging, adjustable open time, and excellent dispensing performance. Additionally, it offers rework ability and impact resistance. It is suitable for bonding and sealing a variety of materials, such as: Structural bonding in mobile electronic devices like smartphones and robotic vacuum cleaners.

Specification

Model	Comp.	Curing Conditions	Color	Open Time min	Viscosity mPa.s	Shear Strength Mpa	Characteristic
APUR101	1K	RT-24H	Light yellow translucent	3-4	3800	ink: 10.5 PC: 14.7	Strong adhesion to metals
APUR101F			Light yellow translucent+ Fluorescence	3-5	4000	SUS: 6.0	
APUR101B			black	3-4	4400	SUS: 6.2	
APUR102			Light yellow translucent	2-4	5200	PC: 16.5	Creep Resistance
APUR102B			black	2-4	6200	ink: 13.3	
APUR103B			black	2-4	5000	ink: 32 PC: 37.8	High impact resistance
APUR104			Light yellow translucent	<1	4800	SUS: 4.8	Rapid curing

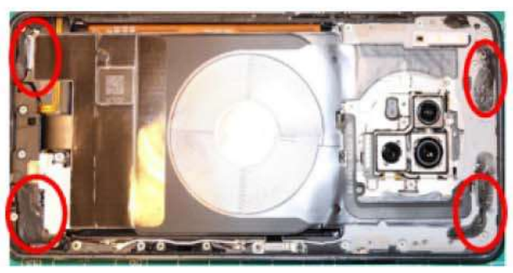
Model	Comp.	Curing Conditions	Color	Open Time min	Viscosity mPa.s	Thermal Conductivity	Shear Strength Mpa	Characteristic
APU201G	2K 1:1	room temperature	Green	31	100000	1.3W	10MPa	High structural bonding + Heat conduction
APU202B	2K 5:1		black	30	1400	/	/	Low shrinkage, Good electrical properties, V0 flame retardancy

*Shear Strength/MP data is based on common interface material to be attached. Please request if there is any other demand.

Application Examples

Mobile Phones TP stick to Middle Frames

Adhesion for cable DOCK heads



Adhesion for components of sweeping robots

Acrylic

StroBond series of acrylics feature outstanding weather resistance and corrosion resistance. They also have excellent adhesion, firmly adhering to various substrate surfaces, including metals, plastics, and woods, and demonstrating superior bonding effects. Additionally, some acrylic products in this series also possess excellent flexibility and ultra-high light transmittance.

Specification

Name	Model	Comp.	Curing Conditions	Color	Open Time min	Viscosity mPa.s	Shear Strength Mpa	Characteristic
MMA	AMAC201	2K 10:1	room temperature	A Comp: Blue B Comp: Yellow	3-5	A: 83000 B: 42000	SUS:＞15	High temperature & High humidity resistance
	AMAC202	2K 10:1		A Comp: Blue B Comp: Amber	4-7	A: 60000 B: 55000	SUS:＞15	Fast curing under heating; slow curing at room temperature
	AMAC203	2K 10:1		A Comp: Blue B Comp: White	5-7	A: 75000 B: 60000	SUS:＞15	Fluorescence

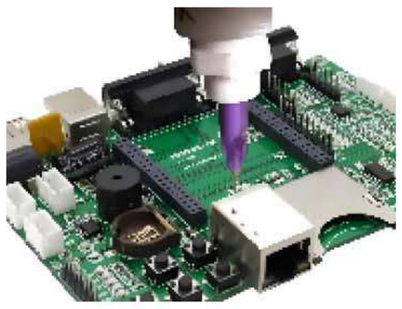
Name	Model	Comp.	Curing Conditions	Color	Viscosity mPa.s	Shear Strength Mpa	Characteristic
UV Cured Adhesive	AUV101	1K	Mercury lamp (electrodeless lamp) 1000mj/cm² or LED light source 365nm (395nm) 3000 - 6000mj	Light yellow translucent	5200	PC/PCB 12 PC/Fe 10 PVC/Al 8	medium viscosity, high bonding strength, low modulus
	AUV102				1300	PC/PCB 16 PC/PC 12	Low modulus, medium viscosity and high thixotropy, resistant to double 85
	AUV103				73670	PVC/PVC 8 PVC/Al 5	Resistant to high temperature and high humidity, cold and heat shock, and salt spray.

Name	Model	Comp.	Curing Conditions	Color	Viscosity mPa.s	Shear Strength Mpa	Characteristic
UV Moisture adhesive	AUVM101	1K	Mercury lamp (electrodeless lamp) 1000mj/cm² or LED light source 365nm (395nm) 3000 - 6000mj +7 days	Light blue translucent	1500	PC/PCB 13 PC/Fe 9	Low viscosity and Low thixotropy
	AUVM102				4000	PC/PCB 12 PC/SUS 8	High hardness, Large curing depth
	AUVM103				4000	PC/PCB 15 PC/Fe 8	High viscosity and Highthixotropy

*Shear Strength/MP data is based on common interface material to be attached. Please request if there is any other demand.

Application Examples

Lens & Holder bonding



Chip corner reinforcement
(non-thermally cured)

Lens Bonding

Epoxy

AlphaPro adhesive strength is established through rapid curing by heating, making it suitable for bonding metal interface materials. It has high bonding strength, low shrinkage, high impedance, and temperature resistance. Common application cases include connector sealing protection, chip underfill, transformer structural bonding, Die Attach, and so on.

Specification

Model	Function	Comp.	Curing Conditions	Color	Viscosity mPa.s	Shear Strength MPa	Tg	Characteristic
EPUF101B	Underfill	1K	130°C@10min	Black	580	15	110	Good fluidity, Fast curing, and Repairable.
EPUF102	Underfill		130°C@10min	Light Yellow	420	15	36	Low Tg and Repairable
EPCR101	Corners Strengthen		80°C@10min	Black	7500	15	30	high thixotropy, high temperature resistance and repairable
EPAA101B	DA Glue		UV3000mj+ 80°C@60min	Black	71000	PCB:17	27	Low shrinkage, Fast curing.
EPAA102B	AA Gule		UV3000mj+ 80°C@60min	Black	71000	PCB:17	26.9	Dual curing, Low shrinkage, Low light transmittan
EPLA103B	LHA Gule		80°C@60min	Black	16000	PCB:18	30.8	Low shrinkage, low precipitation, low light transmittance
AEP104	Structural bonding		60°C @30min	Light Yellow	12500	Al:20	/	low-temperature curing
EP5800	Carbon Fiber Bonding		100°C @90min	Gray	120000	Al:40	120	High Strength, Thixotropic Non Sag Paste

Model	Function	Comp.	Curing conditions	Color	Viscosity mPa.s	Shear Strength Mpa	Shore	Characteristic
AEP201	Sealing protection	2K 1:1	Room temperature	Clear	16000	SUS:15	45	High temperature resistance and Chemical resistance.
AEP202B	Sealing protection	2K 1:1	Room temperature	Black	31000	PVC:5.5	15	Good electrical properties, excellent tensile properties and sealing performance.
EP3050	Optical Component bonding	2K 1:1	80°C @40min	Light Brown	3000	135	85	Reasonable pot-life, resisting >200°C

*Shear Strength/MP data is based on common interface material to be attached. Please request if there is any other demand.

Electronic-grade Adhesive

Silicone

AlphaPro can provide a wide variety of silicone products. Common application scenarios include electromagnetic shielding CIPG, sealing protection of components on PCBs, and reinforcement of FPCs. It has rapid positioning and excellent adhesion to multiple substrates. It also has excellent high-temperature resistance. At the same time, it can provide thermal management for heat sinks, memory and chips, power transistors and CPUs, etc., including potting protection for photovoltaic, wind power, energy storage systems and on-board charger inverters OBC.

Specification

Name	Model	Function	Comp.	Curing Conditions	Color	Viscosity mPa.s	Shear Strength	Hardness shore
RTV Silicone	ASIR101W	Sealing protection	1K	RT 7days	○ White	1000000	Al: 1.8	48A
	ASIR102			RT 7days	◯ Half-Clear	57000	Al: 1.5	23A
	ASIR103B	Potting protection	1K	RT 7days	● Black	40000	Al: 1.6	35A
Organic Silicone	ASIL201W		2K 1:6	RT 3days	○ White	3000	/	45A

Functional Composite Materials

Thermal Management Tape

AlphaPro™ thermal management tape 150X series have excellent thermal conductivity and outstanding adhesive properties, and have good wettability on different surfaces, which helps to maximize the thermal conductivity efficiency of electronic devices. The thickness ranges from ultra-thin 10μm to 100μm, providing more flexibility for component design.

Specification

Name	Model	Type	Wetting	Thickness μm	Peel Adhesion N/cm	Break Down Voltage kV	Thermal Conductivity W/m·K
Thermal Management Tapes	1506	Thermally conductive acrylic	78%	10	3.5	＞0.5	0.6W
	1507		86%	100	5.0	＞2.0	1.0W

*Shear Strength/MP data is based on common interface material to be attached. Please request if there is any other demand.

Thermal Management

AlphaPro series includes thermal conductive gel, grease and potting compound, fully meeting the heat dissipation requirements of electronic devices. Thermal gel is soft and compressible to 0.1mm, with low contact thermal resistance, and suitable for automated production. Thermal grease features high thermal conductivity and low thermal resistance, a wide temperature range (-50°C to 230°C), widely used for heat dissipation of CPUs, GPUs, etc. Thermal potting compound has good insulation and high-temperature resistance.

Specification

Name	Model	Color	Shore Shore	Density g/cm³	Dielectric Constant	Thermal Conductivity Coefficient
Thermal Pad	TP40-2	Gray Blue	40	2.8	5.8	2
	TP50-6	Gray	50	3.3	8.0	6
	TP60-12	Gray	60	3.3	9.0	17

Name	Model	Color	Hardness Shore A	Viscosity After Mixed cPs	Dielectric Strength kV/mm,AC	Thermal Conductivity W/(m.K)
Thermal Potting Compound	TP2001	Gray	20 ~ 25	2500~3000	> 2.0	1.0
	TP2035	Gray	60 ~ 65	24000~25000	> 5.0	3.5

Name	Model	Color	Density g/cm³	Dielectric Constant	Thermal Conductivity Coefficient W/(m.K)
One-Component Thermal Gel	TG1-4	Green	3.4	7.0	4.0
	TG1-7	Gray	3.4	8.7	7
	TG1-10	Red	3.5	9.0	12
Two-Component Thermal Gel	TG2-4	A: Blue B: White	3.3	6.8	4.0
	TG2-6		3.5	7.3	6

Name	Model	Color	Density g/cm³	Thermal Resistance °C*in²/W@40psi	Thermal Conductivity W/(m.K)	Characteristic
Thermal Grease	ASIG102G	Gray	2.6	0.06	3.5	Low thermal resistance, high thermal conductivity, good electrical insulation, excellent fluidity, suitable for low-clearance scenarios
	ASIG103G	Gray	3.1	0.04	6.5	
	ASIG101G	Pink	3.7	0.02	10.0	

*Shear Strength/MP data is based on common interface material to be attached. Please request if there is any other demand.

Electronic-grade Adhesive

Hot Melt Adhesives

AlphaPro's hot melt adhesives can bond many substrates that are difficult to bond, including metals, plastics, woods, leathers, fabrics, non-woven fabrics and foils. Common application scenarios include but are not limited to chip bonding applications, capping connections of wire-bonded packaged devices, ball grid array packaging, gap filling in smart home appliances, etc.

Specification

Name	Model	Total Thickness μm	Material	Hot Melt Temperature	Mechanical Parameters
Low-temperature thermosetting adhesive film	ATSAF80	80	PU	70-80℃	PEAL Force＞40N
Thermoplastic film	ATPAF50	50		110-130℃	
Pressure-Sensitive Hot Melt Adhesive	PSHAF03	/	Rubber	160-180℃	Sheer Strength＞0.3Mpa Sheer Strength＞0.8Mpa
Pressure-Sensitive Hot Melt Adhesive	PSHAF08				

*Shear Strength/MP data is based on common interface material to be attached. Please request if there is any other demand.

Functional Composite Materials

Protection Film

Our process protection film has the advantages of good selfwetting, anti-static, low adhesion, high temperature resistance, and no residual adhesive. It can protect glass, plastic, metal and other structural parts of various high-end equipment during the assembly process.

Specification

Name	Type	Model	Material	Adhesive	Color	Total Thickness μm	Peal Force g/cm
Silicone Protective Film	Single-Sided Tape	SPTS35-200	PET	Silicone	Clear Blue Red Yellow	35-200	1-800
Acrylic Protective Film		SPTA35-200	PET	MMA		35-200	1-800
PU Protective Film		SPTP50/75	PET	PU	Clear Blue Red	50/75	1-20

*Shear Strength/MP data is based on common interface material to be attached. Please request if there is any other demand.

Star Series

Wafer Processing Tape

Alphapro wafer dicing tape is not only suitable for ordinary wafers but also meets the cutting needs of small and medium-sized wafers. This tape has strong adhesion, good elasticity, and is very stable. Its function is to firmly fix the wafer during cutting to prevent the chips on it from falling off. At the same time, due to tape's sensitivity to ultraviolet light, the stickiness becomes smaller under UV light. The cut wafer can be easily uncovered without leaving any residue. It ensures cutting accuracy and also improves the efficiency of chip collection.

Specification

Name	Model	Total Thickness μm	Substrate	Viscosity Before/After Peel N/cm	Debonding Process	Color
BG Tape	ABGT110	110	PO	Si: 0.8/0.8	Non-UV	Blue
Dicing Tape	ADCT90	90	PO	Si: 3.2/0.05	UV intensity：230mW/cm2 UV Energy：300mJ/cm2	Blue
	ADCT110	110	PO	Si: 5/0.08	UV intensity：230mW/cm2 UV Energy：300mJ/cm2	
	ADCT170	170	PO	Si: 8.8/0.01	UV intensity：230mW/cm2 UV Energy：300mJ/cm2	
Non-UV Curable Dicing Tape	AHDB70	70	PET	Si: 2.4/0.04	90°C/1-5mins	Opaque
	AHDB110	110	PET	Si > 2.4/ 0.06	90°C/1-5mins	
QFN Masking Tape	CQMT30	30	PI	Roll pressing：0.1 Heat lamination：2.2 (<230°C)	/	Brown
	CQMT40	40	PI	Roll pressing：0.1 Heat lamination：2.5 (<230°C)	/	
UV Releasing Adhesive Tape	AUVDB65	65	PET	＞3.2 / 0.04-0.08	3000mJ/10s LED 365nm	Opaque
	AUVDB95	95	PET	＞3.2 / 0.04-0.08	3000mJ/10s LED 365nm	

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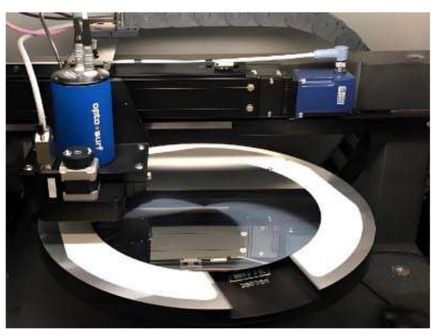
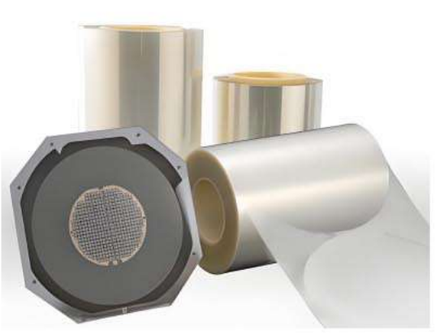
Application Examples

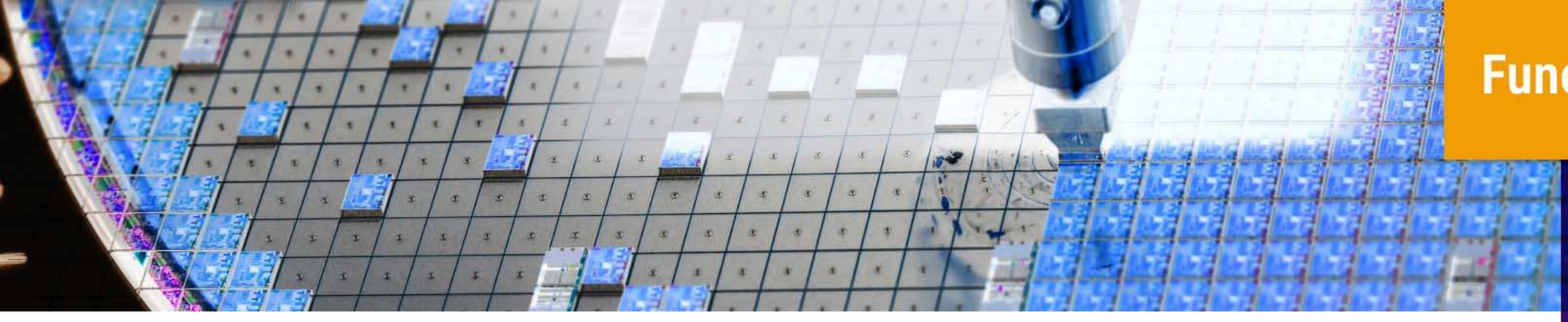


wafer back grinding process

wafer dicing process



wafer adhesive film series



Covering Tapes

With the continuous development and iteration of the electronic component industry, AlphaPro is also striving to provide advanced technical solutions for customers. Common application cases include but are not limited to LCD backlight module shading, FPC insulation protection, battery insulation bonding, PCB anti-static protection, transformerlcoil bundling, etc.

Specification

Name	Model	Adhesive Type	Color	Total Thickness μm	Peel Force N/cm	Holding power@ 8-25°C >72 hours
PET Insulating Single-Sided Adhesive Tape	SPTA10MB/B	Acrylic	Matte Black Black	10	>2	
	SPTA30MB/B			30	>3	
	SPTA100MB/B			100	>4	
PI Single-Sided Adhesive Tape	SPIA20/20MB		Brown Matte Black	20	>2.4	
	SPIA50/50MB			50	>4	
	SPIA100/100MB			100	>5	
Anti-Static PET Single-Sided Adhesive Tape	SPTA50E			50	>4	
	SPTA60E			60	>4	
Anti-Static & High-Temperature Resistant PI Tape	SPIS50E	Silicone Gel	Clear	50	>2	
	SPIS60E			60	>2.4	
High-Temperature Resistant PI Tape	SPIS50E		Brown	50	>2	
	SPIS100			100	>4	

*Shear Strength/MP data is based on common interface material to be attached. Please request if there is any other demand.

Product Advantage

- Anti-Lifting
- Light shielding
- High Viscosity
- Matte Black Design

Double-Sided Tape

AlphaPro's general bonding solution has good initial adhesion and bonding performance, which is suitable for general fixation and lamination. This series of products uses PET/PI film as the substrate and is easy to die-cut. We can flexibly provide solutions ranging from 5um to 200um, giving you more choices

Specification

Holding power@ 8-25°C >72 hours

Name	Model	Color	Total Thickness μm	Peel Force N/cm
PET Double-Sided Adhesive Tape	DPA05	Clear Black Yellow Blue Red	5	>2.4
	DPA10		10	>2.4
	DPA50		50	>4.8
	DPA100		100	>6
	DPA150	clear black blue red	150	>6
	DPA200		200	>8
Tissue Double-Sided Adhesive Tape	DTA60	black half-clear	60	>4
	DTA150		150	>6
	DTA200	half clear	200	>8

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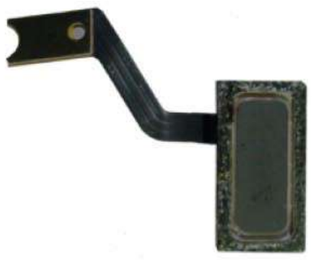
Application Examples

Cables fixation

FPC reverse fixation

Motherboard fixation & grounding



Vibration motor bonding

Foam Tape

AlphaPro's foam tape solution takes into account both viscosity and elasticity. While ensuring internal cohesion, it can effectively absorb and slow down mechanical stress. Ensure that it can exhibit excellent performance throughout the life cycle of electronic products, such as outstanding impact resistance, long-term bonding stability and good waterproof ability

Specification

Holding power @ 8-25°C >72 hours

Name	Model	Classic Applications	Color	Total Thickness μm	Peel Force N/cm
Ultra-Thin Waterproof PE Foam Double-Sided Tape	DPEF100-400WP	Back cover pasting, camera lens bonding, display screen bottom bonding, wearable device bonding	● Black	100-400	>6
Ordinary PE Foam Double-Sided Adhesive Tape	DPEF150B/G/W		● black ● grey ○ white	150	>6
	DPEF200B/G/W			200	>6
	DPEF250B/G/W			250	>6
	DPEF300B/G/W			300	>6
	DPEF500B/G/W			500	>8
	DPEF1000B/G			1000	>10
	DPEF1500B/G			1500	>10
Acrylic Foam Double-Sided Adhesive Tape	DACF400		● grey	400	>10
	DACF600		● grey	600	>10
	DACF1000		● grey	1000	>15

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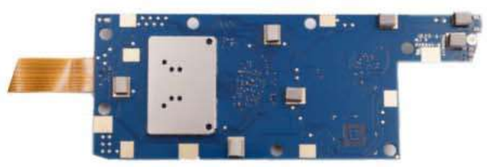
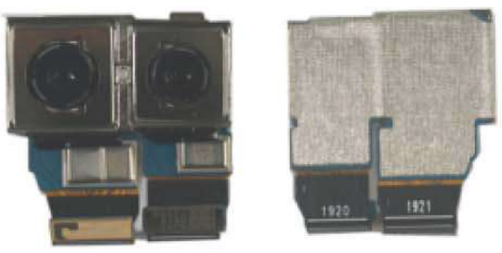
Application Examples

Foam bonding



Grounding of Smart Home Motherboard



Camera bonding & grounding

Electrically Conductive Tapes

AlphaPro's conductive tape series can meet the latest requirements for shielding, grounding, gap filling, good appearance, etc., which can also cover various common applications, including motherboard covering, motherboard shielding, wire wrapping, display module edging, FPC grounding, etc

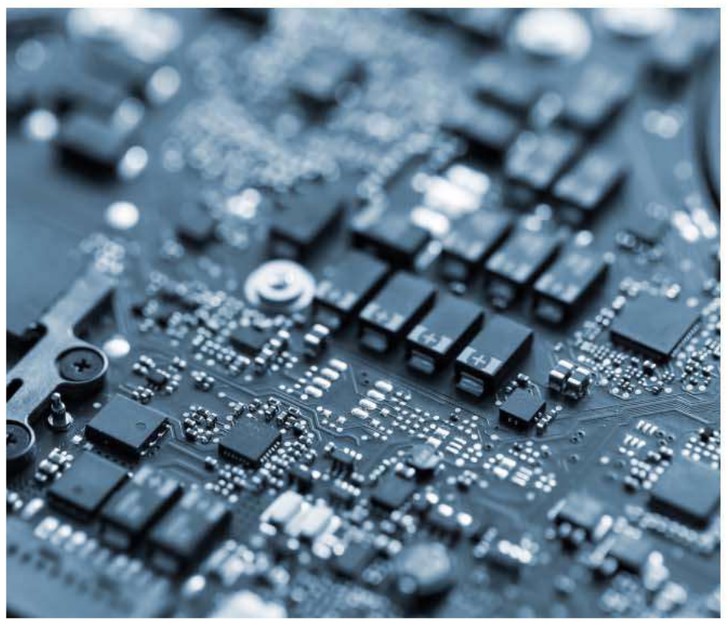
Specification

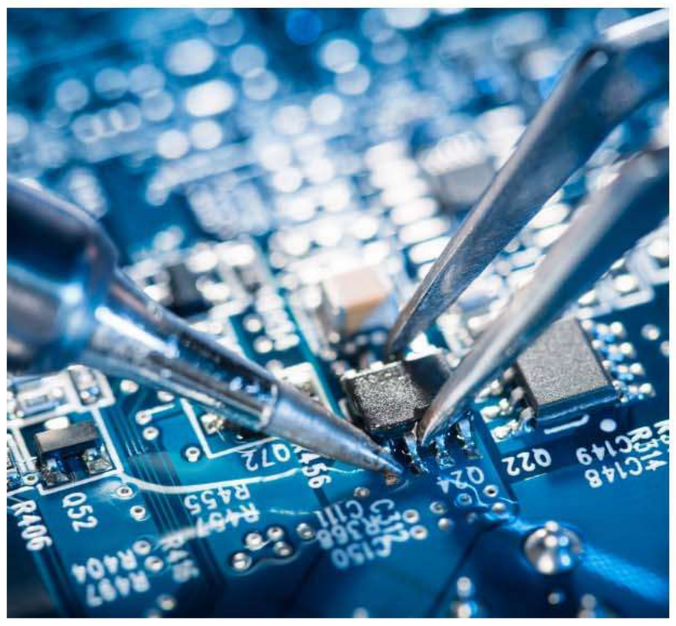
Name	Model	Color	Total Thickness μm	Peel Force N/cm	Vertical Resistance⊥ Ω
Conductive Fabric Single-Sided Tape	SCF30	Grey	30	>2.4	≤0.08
	SCF50B	Black	50	>3	
	SCF120		120	>4	
	SCF150		150	>4	
Conductive Fabric Double-Sided Tape	DCF30		30	>2.4	
	DCF50		50	>3	
	DCF80		80	>4	
	DCF150		150	>4	
	DCF200	Grey	200	>6	
Double-Sided Conductive Fabric Tape With Different Strengths	DCF50SW		50	A: >3.2 B: <2	
	DCF100SW		100	A: >4 B: <2	
Conductive Non-Woven Double-Sided Tape	DCN30		30	>2.4	
	DCN50		50	>4	
	DCN65		65	>4	
	DCN100		100	>4	
Double-Sided Conductive Non-Woven Tape With Different Strengths	DCN50SW		50	A: >3.2 B: <2	
	DCN100SW		100	A: >4 B: <2	
Conductive Copper Foil Single-Sided Tape	SCC30	Golden	30	>2.4	
	SCC50		50	>3	
	SCC100		100	>4	
	SCA50	Silver	50	>3	
	SCA100		100	>4	

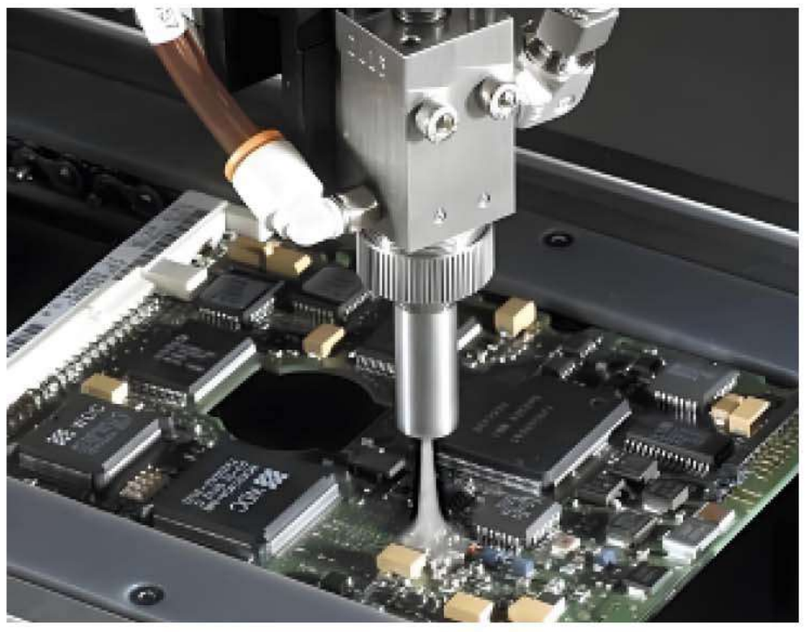
Name	Model	Color	Total Thickness μm	Peel Force N/cm	Vertical Resistance⊥ Ω
Matte Black Copper Foil Mylar	SCM30	● Black	30	>3	/
	SCM50		50	>4	
	SAM50		50	>4	
	SAM55		55	>4	
Omnidirectional Conductive Foam	SFF150	● Grey	150	>2	≤0.08
	SFF300		300	>3	
	SFF500		500	>3	
	SFF1000		1000	>4	
	SFF1500		1500	>4	

*Shear Strength/MP data is based on common interface material to be attached. Please request if there is any other demand.

Application Examples







Main board coverage

TP Display module electromagnetic shielding

Bundle wrapping

Irregularly Shaped Wrapped Foam

AlphaPro's solution takes into account both viscosity and elasticity. While ensuring internal cohesion, it can effectively absorb and slow down mechanical stress. Ensure that it can exhibit excellent performance throughout the life cycle of electronic products, such as outstanding impact resistance, long-term bonding stability and good waterproof ability.

Product Advantage

- High Viscosity
- High Conductivity
- Anti-Rebound
- EMI Shielding
- Compressibility

Specification

Name	Model	Color	Compressibility	Peel Force Kg/inch	Vertical Resistance⊥
C-Shaped Half-Wrapped Foam	CHF-Any	Grey Golden Silver	70-80%	>0.8	Ω ≤0.08
C-Shaped Full-Wrapped Foam	CAF-Any				

*Shear Strength/MP data is based on common interface material to be attached. Please request if there is any other demand.

07

No Carrier Adhesive Films

There is no substrate between the adhesive layer of the substrate-free tape and the carrier material, so the force released by the glue is stronger. Therefore, it has higher viscosity and better mechanical strength. This characteristic can be applied to products that need to be used in high-viscosity and high-tension environments, such as cable fixation, waterproof sealing, fixation of circuit boards, and mobile phone back stickers.

Specification

	Model	Total Thickness μm	Adhesive	Peel Force N/cm	Holding Powers
Double-Sided Adhesive Without Substrate	DCAF50	50	Acrylic	>6	@70℃＞72H
	DCAF100	100		8±2	
	DCAF130	130		9.5±3.5	

*Shear Strength/MP data is based on common interface material to be attached. Please request if there is any other demand.

Electronic-grade Adhesive

Conformal Coating

AlphaPro's existing solutions include silicone conformal coatings, which are suitable for outdoor equipment, high-power products, and automotive electronic products; while commonly seen ones are mainly acrylic conformal coatings, which are applicable to smart wearable devices, medical devices, household appliance equipment, etc.

Specification

Adhesive Type	Model	Curing Conditions	Hardness Shore	Viscosity mPa.s	surface drying time	Characteristic
Acrylic	UMCA-01	Mercury Lamp （Electrodeless Lamp） 1000mj/Cm² Or LED Light Source 365nm (395nm） 3000-6000mj + RT 7days	35	150	12-30s	Drying Quickly, Good UV Resistance, Wide Temperature Tolerance Range
Acrylic	UMCA-05		55	3500	12-30s	
Silicone	MSC-01	Room Temperature	32	350	<10min	Resistant To Ultraviolet Radiation, Good Weather Resistance
Silicone	MSC-01		25	30000	<15min	

*Shear Strength/MP data is based on common interface material to be attached. Please request if there is any other demand.

Polymer Bio-based Materials

Polymer Bio-based Materials

Biodegradable tape is a kind of tape made of degradable materials. In the natural environment, it can be quickly decomposed into carbohydrates, water and carbon dioxide through the biodegradation process. The principle is that through the action of microorganisms, enzymes or other bioactive factors, the polymer chain is broken down into low molecular weight compounds. Common biodegradable tape materials include starch, polylactic acid (PLA), polyhydroxyalkanoates (PHA),etc.

Biodegradable tape can replace traditional tape and play a role in fixing, sealing and protecting in electronic industry applications such as foam bonding, flexible circuit board fixation, and parts pasting, reducing the impact on the environment.

Specification

Type	Model	Total Thickness μm	Steel Plate Peel Force N/cm	High Temperature Holding Power	Bio-Based Carbon Content
Bio-based PSA	ABIOP10	10	>4	@70°C＞72H	＞70%
	ABIOP25	25	＞6		
	ABIOP50	50	＞8		
	ABIOP75	75	＞10		

*Shear Strength/MP data is based on common interface material to be attached. Please request if there is any other demand.

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Official Website Message

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